Product Change Notification

■ Purpose

[2023-03-22] Sharp Corporation would like to notify customers of an update to a previously announced PCN (Feb. 21, 2022 and Oct. 3, 2022) regarding change of an internal **signal processing IC** used in the following Sharp distance measuring sensor models:

- GP2Y0A02YK0F
- GP2Y0A21YK0F
- GP2Y0A41SK0F
- GP2Y0A51SK0F
- GP2Y0AF15X
- GP2Y0D02YK0F
- GP2Y0D21YK0F

Originally, Sharp indicated the existing signal processing IC used in these Sharp sensors would be changed to an entirely new IC made by UMC Taiwan. This would have been a major change.

However, the situation has now changed and Sharp will continue using the existing signal processing IC except that the IC will be manufactured by JS Foundry in Japan. This change of IC manufacturer is a much smaller change.

There will be no changes to the Sharp business part number, product shape, pin arrangement, product characteristics or reliability.

■ Effective Time of Change

These are running changes that will be applied starting in February, 2024.

■ Details

Please refer to the pages that follow for more details concerning the changes.

If you have any questions concerning this notification, please contact your Socle representatives at: Socle_Sales_NA@socle-tech.com

17th March, 2023	
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SHARP Products Change Notification

Sharp Semiconductor Innovation Corporation

Product Planning Div.
M.Watanabe

Thank you very much for your continuous usage
of our semiconductor device products.
We would like to inform the change of Distance measuring sensor as follows.

Subject	**Notification of the Change in Manufacturing Contractor of DMS Signal Processing IC**

Applicable Product Category	**All distance measuring sensor models**
Changed From	**Running change is scheduled for February 2024 onward.** ※Depending on the sales situation, the schedule may change.

We would like to inform our customers of the policy change in regards to the change in manufacturer of DMS signal processing IC.

We have recently made a request for our customers to make a switch to the DMS equipped with signal processing IC manufactured at the UMC factory.
This time however, we have made it possible to have our designed and developed in-house IC to be manufactured by JS Foundry, which had bought over the production factory of the current IC.
By mounting this IC, there will be no changes to existing substrates (layout), capacitors, resistors and lead frames.
In addition, we have planned for the signal processing IC to be manufactured on the same production lines and facilities as the current IC, resulting in minimum changes from the current DMS.

Based on the above, we would like to inform you that JS Foundry will be the manufacturing contractor for signal processing IC, and that we will continue to produce the DMS.

We would like to sincerely apologize to our customers for your time spent on evaluating the switch to UMC products.
We apologize for the change in policy, but we greatly appreciate your cooperation in continuing to adopt our products.

1. Applicable to all DMS models
2. Content of change
   Change in manufacturing factory
   (Manufacturing contractor in previous notice) UMC, Taiwan
   (Manufacturing contractor after change) JS Foundry Niigata, Japan
3. Reason for change: For continuous supply of DMS

There is no change in the external part number, product shape, pin arrangement, product characteristics and reliability.

測距用信号処理IC変更 対象機種/Applicable distance measuring sensors

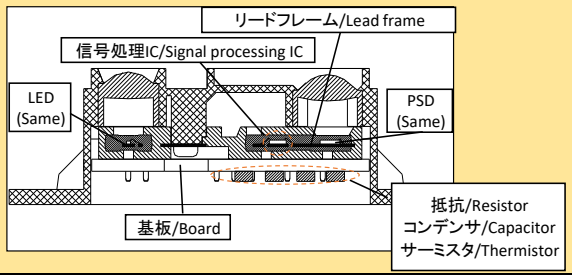
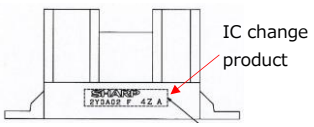
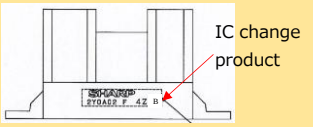
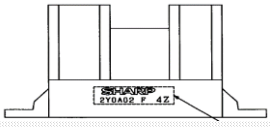
系列/Series	タイプ/Type	社外品番/ Applicable Model No.	現行 社内品番/ Current Internal Model No.	新 社内品番/ New Internal Model No.
GP2Y系列	アナログ出力 Analog output	GP2Y0A02YK0F	GP2Y0A02YKF4	GP2Y0A02YKFB
		GP2Y0A21YK1F	GP2Y0A21YK16	GP2Y0A21YK1B
		GP2Y0A21YK0F	GP2Y0A21YKF4	GP2Y0A21YKFB
		GP2Y0A51SK0F	GP2Y0A51SK04	GP2Y0A51SK0B
		GP2Y0A41SK0F	GP2Y0A41SKF4	GP2Y0A41SKFB
		GP2Y0A02YK1F	GP2Y0A02YK14	GP2Y0A02YK1B
	デジタル出力 Digital output （1bit）	GP2Y0D02YK0F	GP2Y0D02YKF4	GP2Y0D02YKFB
		GP2Y0D21YK0F	GP2Y0D21YKF4	GP2Y0D21YKFB
		GP2Y0D417KBF	GP2Y0D417KB4	GP2Y0D417KBB
GP3Y系列	デジタル出力 Digital output （1bit）	GP3Y0D013K	GP3Y0D013K26	GP3Y0D013K2B
		GP3Y0D026K0F	GP3Y0D026K06	GP3Y0D026K0B
		GP3Y0D026KAF	GP3Y0D026KA6	GP3Y0D026KAB
		GP3Y0D031K0F	GP3Y0D031K06	GP3Y0D031K0B
		GP3Y0D032K0F	GP3Y0D032K06	GP3Y0D032K0B
		GP3Y0D033K0F	GP3Y0D033K06	GP3Y0D033K0B
		GP3Y0D418K0F	GP3Y0D418K04	GP3Y0D418K0B
GP2Y0AF系列 /Series （小型測距 /Small type)	アナログ出力 Analog output	GP2Y0AF15R	GP2Y0AF15R04	GP2Y0AF15R0B
		GP2Y0AF15X	GP2Y0AF15X04	GP2Y0AF15X0B
		GP2Y0AF15XR	GP2Y0AF15XR4	GP2Y0AF15XRB
		GP2Y0AF15Q	GP2Y0AF15Q04	GP2Y0AF15Q0B
		GP2Y0AF15Y	GP2Y0AF15Y04	GP2Y0AF15Y0B
		GP2Y0AF15Y	GP2Y0AF15YS4	GP2Y0AF15YSB
		GP2Y0AF30Q	GP2Y0AF30Q04	GP2Y0AF30Q0B
		GP2Y0AF30R	GP2Y0AF30R04	GP2Y0AF30R0B
		GP2Y0AF30S	GP2Y0AF30S04	GP2Y0AF30S0B
		GP2Y0AF30Y	GP2Y0AF30Y04	GP2Y0AF30Y0B

2023/03/17

SHARP測距センサ 信号処理IC変更に関する比較表
Comparison sheet related on material change for SHARP Distance sensor

【適応機種/Applicable Model】 測距センサ全モデル/All models

シャープセミコンダクターイノベーション株式会社
Sharp Semiconductor Innovation Corporation

			前回変更後/After 1st Change	今回変更後/After 2nd Change	現行/Before Change
社外品番/Applicable Model No.			全機種/All models (Same)		
Country of Origin / Manufacturing Location			中国／珠海縁成電子 China ／ Zhuhai Ensei Electronics Co., Ltd. (Same)		
材料/ Materials	信号処理IC /Signal processing IC	1) IC仕様/IC Spec.	端子配置・機能変更有り /Pin assign・Function changed	現行と同一/Same	←
		2) Wafer製造工場 /Wafer Factory	UMC,Taiwan	JS FOUNDRY, Japan	Current factory, Japan
	3)-①基板/Board		ICに合わせた配線パターン変更 /Layout pattern changed to fit new IC (詳細は別添資料参照)	現行と同一/Same	←
	3)-②抵抗/Resistor		ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	現行と同一/Same	←
	3)-③コンデンサ/Capacitor		ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	現行と同一/Same	←
	3)-④ リードフレーム/Lead frame		ICに合わせたフレーム変更 / Frame changed to fit new IC (一部機種のみ / Only some models)	現行と同一/Same	←
	断面図/Cross section (参考/Reference)				
	その他部材(LED, PSD, Lensつきモールドケース等) /The other materials(LED, PSD, Lens mold case, etc.)		現行と同一/Same		
電気的特性 / Electronic spec. (絶対最大定格含む/ Including absolute maximum rating.)			現行と同一/Same		
QC工程 / QC process			現行と同一/Same		
製品信頼性 / Product Reliability			現行と同一/Same		
外形図/ Outline Dimension			現行と同一/Same		
マーク/ Marking					
梱包仕様 / Package spec			現行と同一/Same		